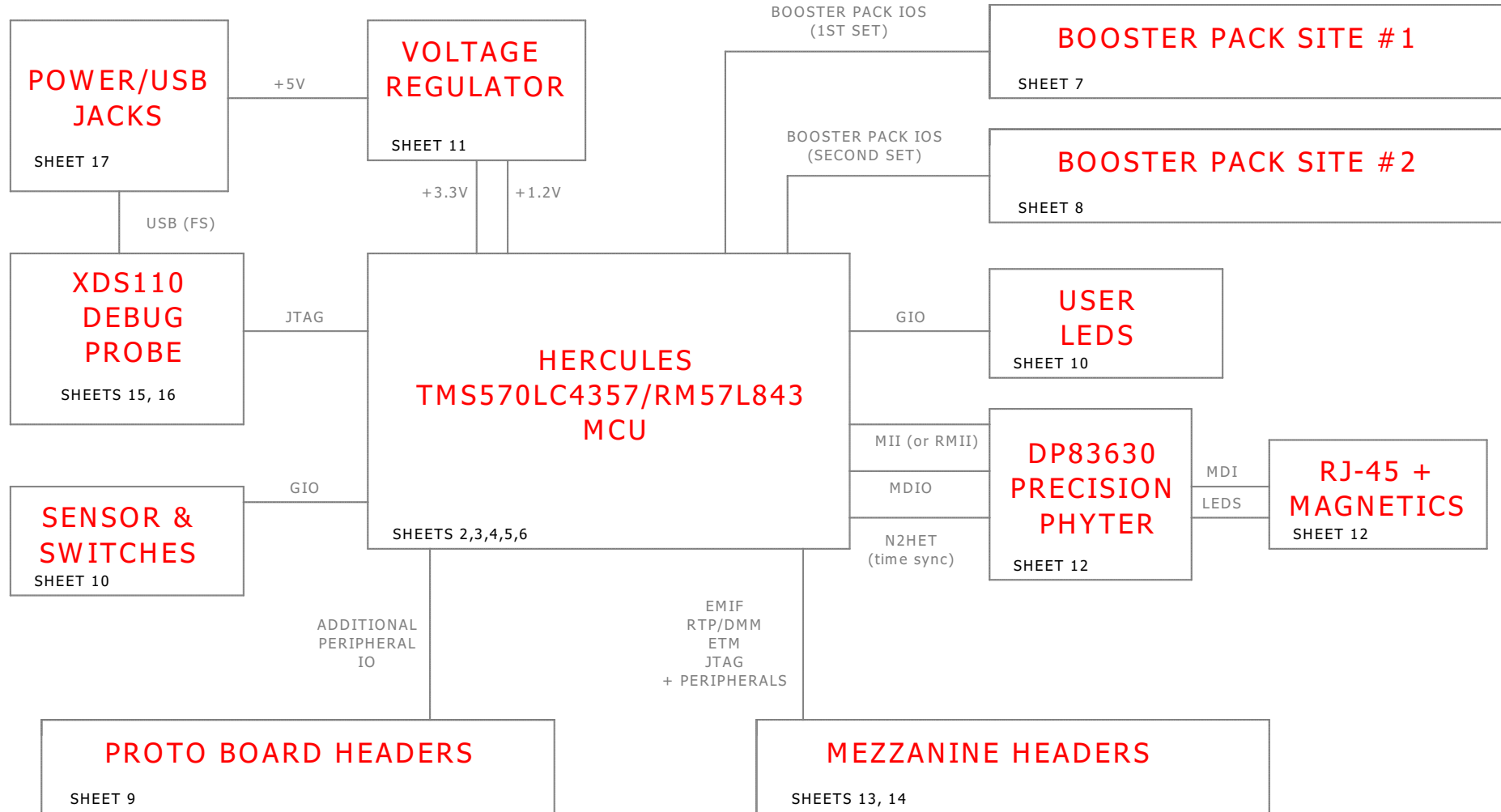


# LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

## 337 ZWT LAUNCHPAD XL2



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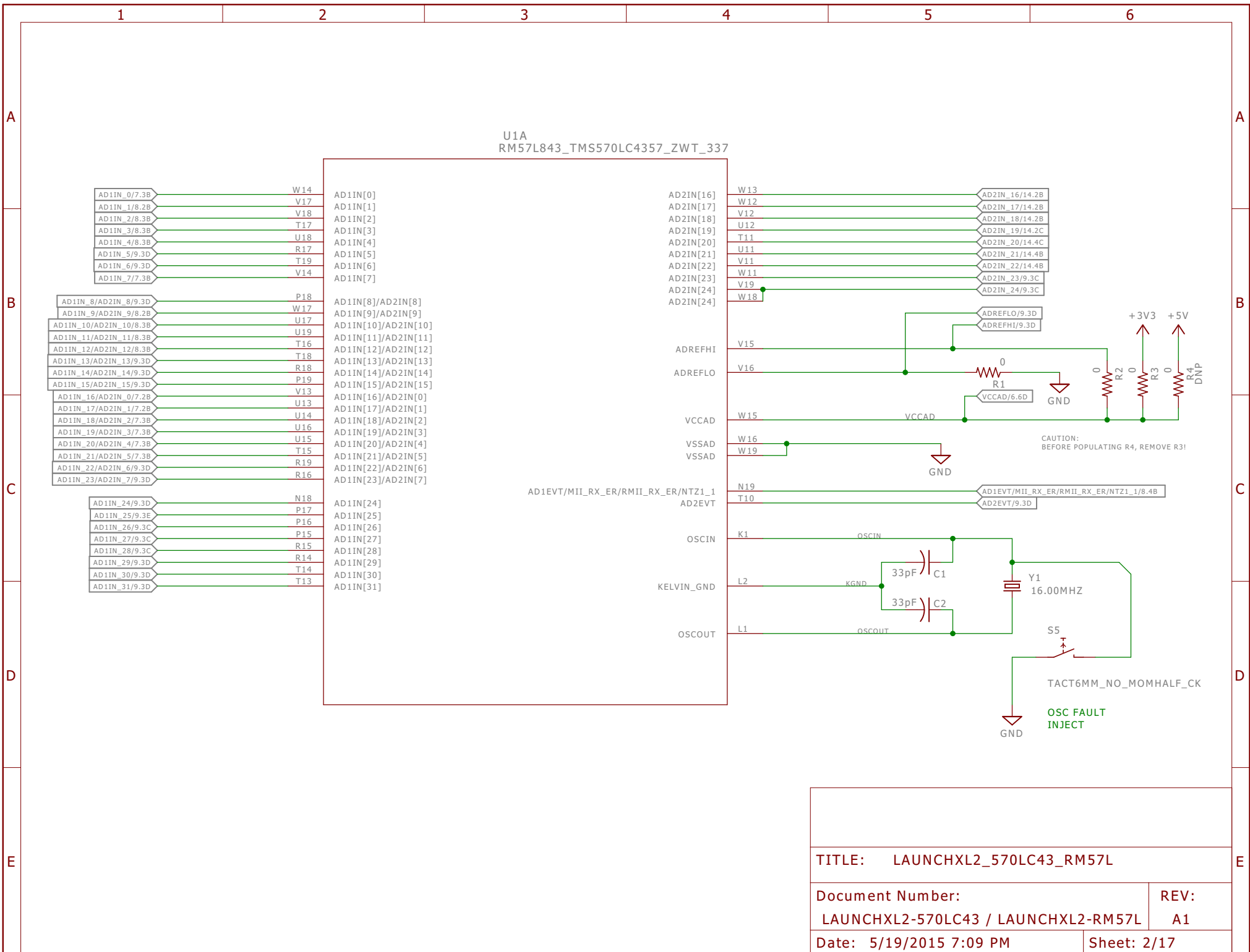
LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

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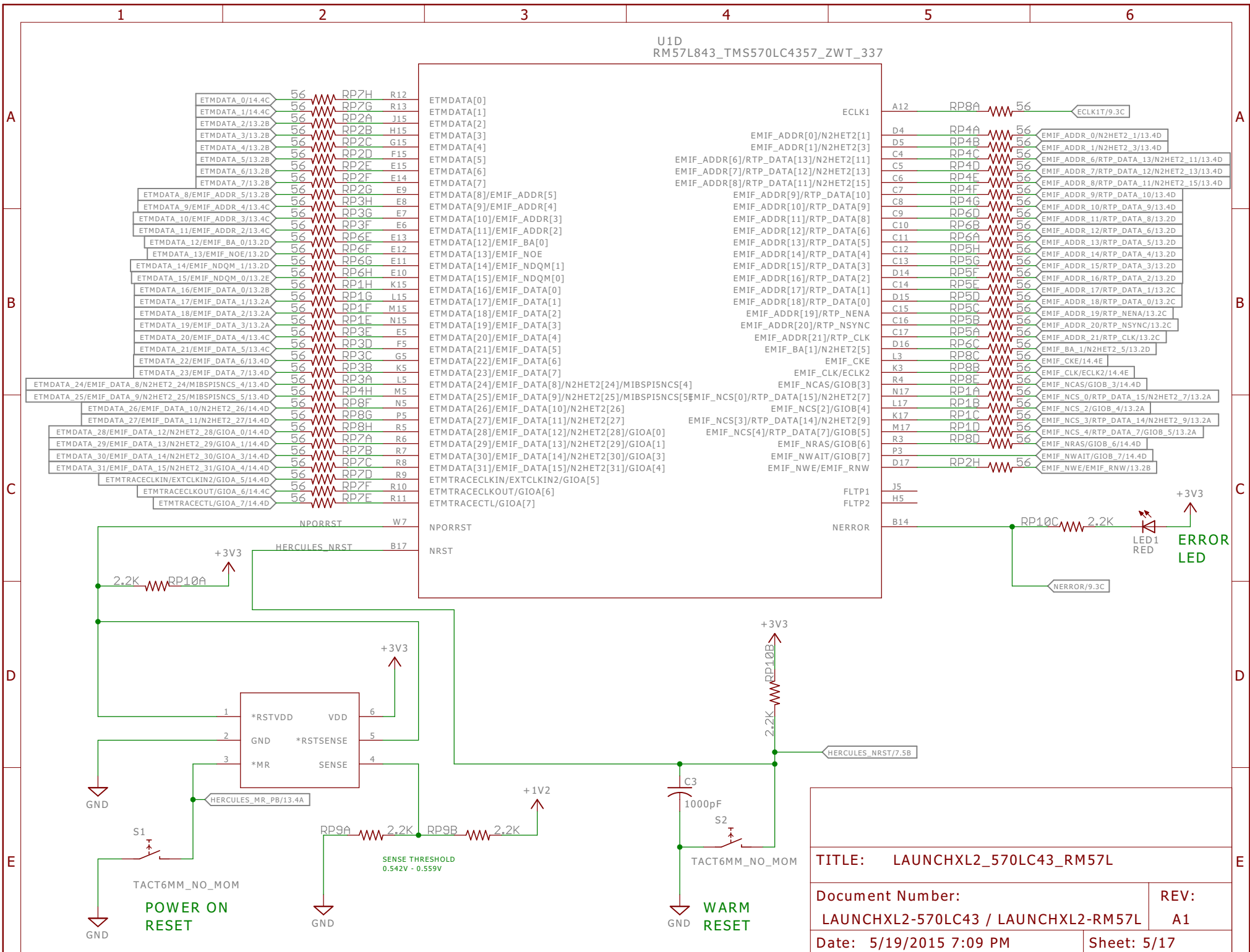
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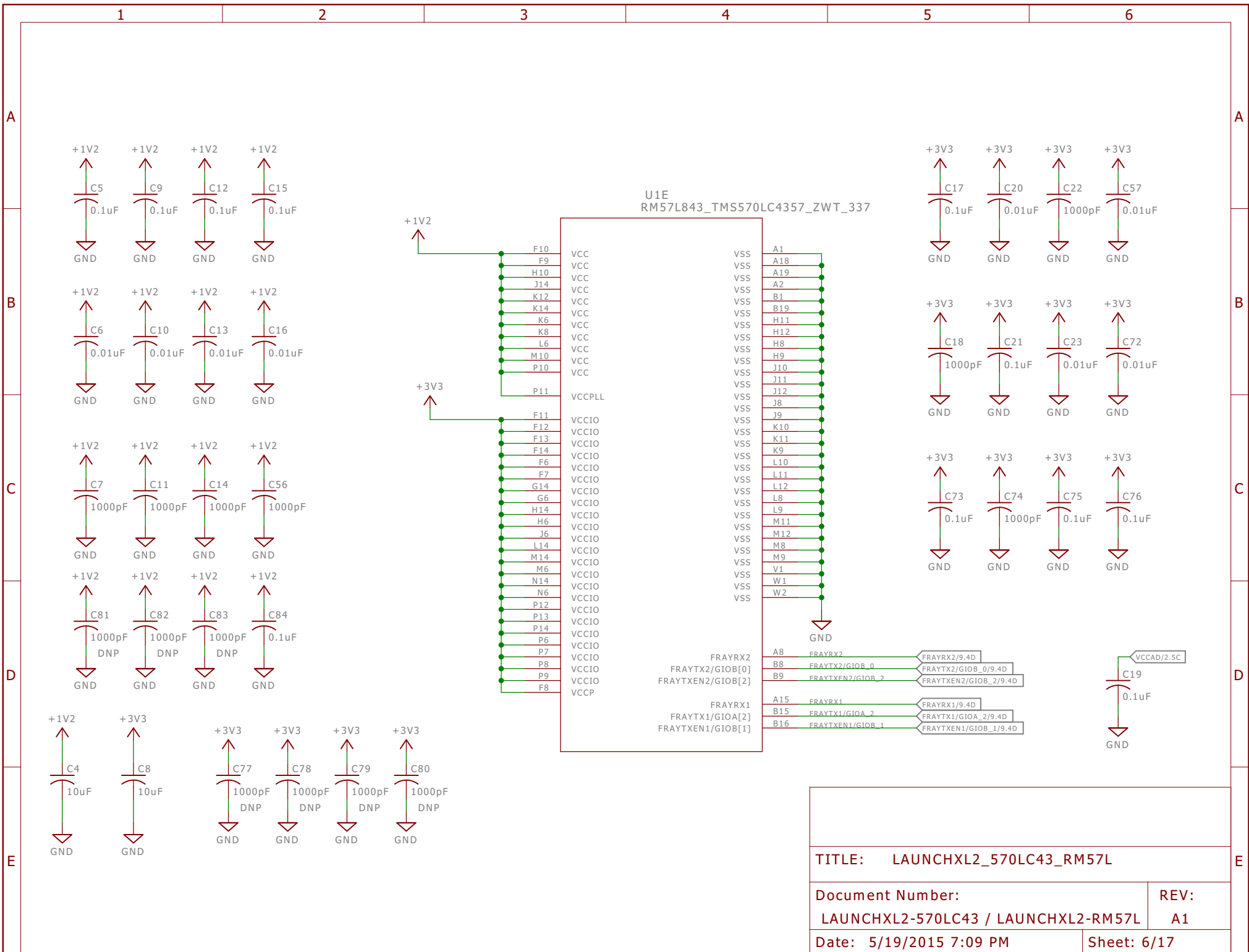
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RM57L843\_TMS570LC4357\_ZWT\_337



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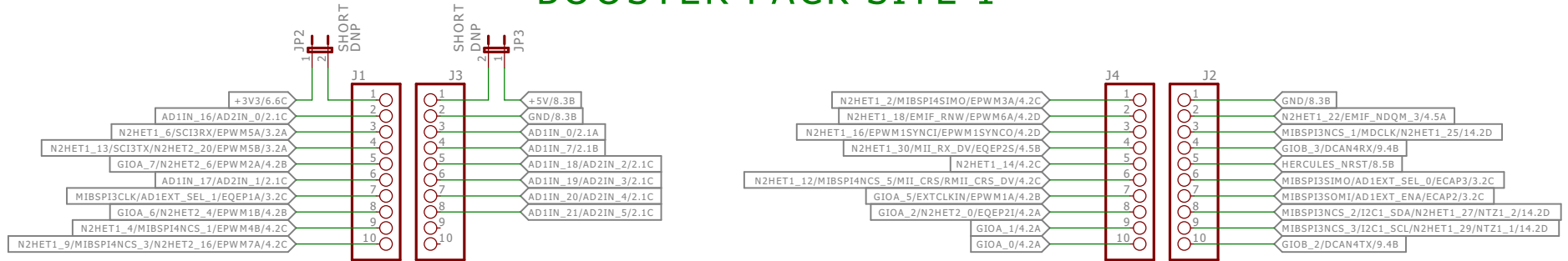
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## BOOSTER PACK SITE 1



Headers/Receptacles may be ordered from <http://launchpad.mlelectronics.com/>

### NOTES:

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JP2 & JP3 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP2,JP3 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

TITLE: LAUNCHXL2\_570LC43\_RM57L

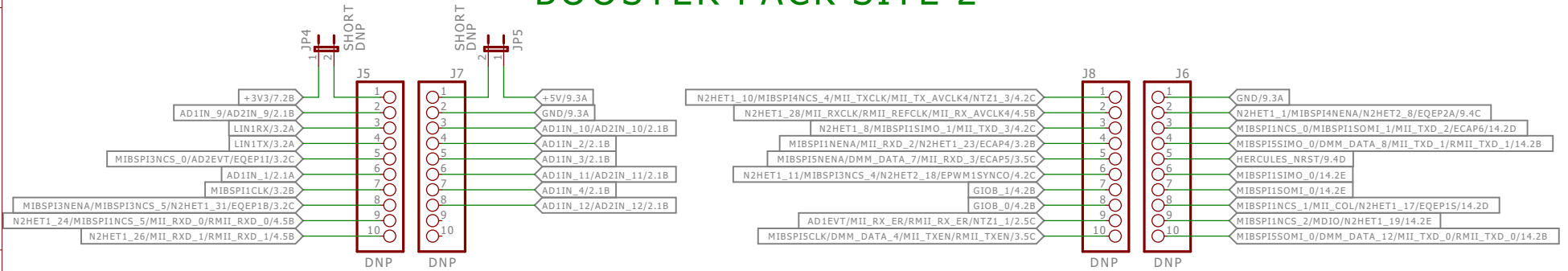
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LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

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## BOOSTER PACK SITE 2



Headers/Receptacles may be ordered from <http://launchpad.mlelectronics.com/>

**NOTES:**

JP4 & JP5 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP4,JP5 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

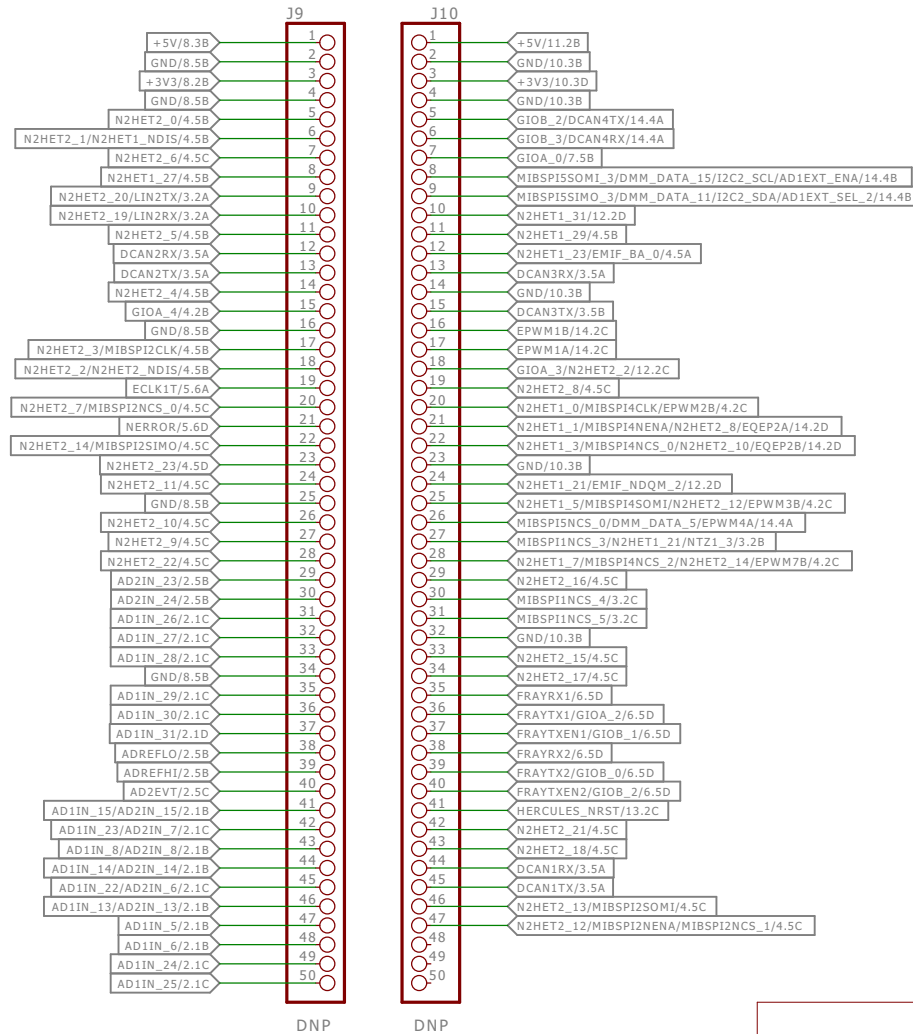
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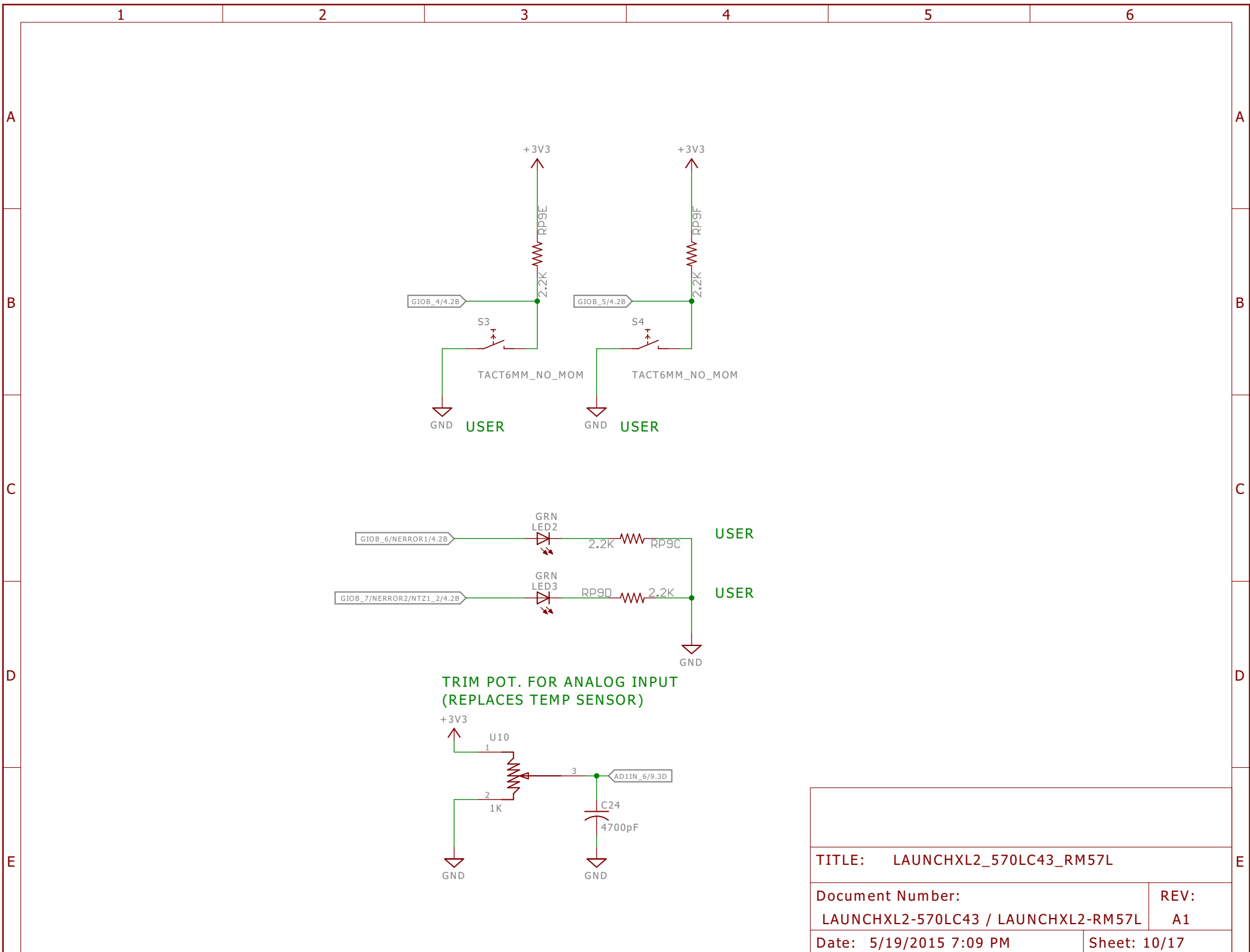
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# PROTO BOARD HEADERS

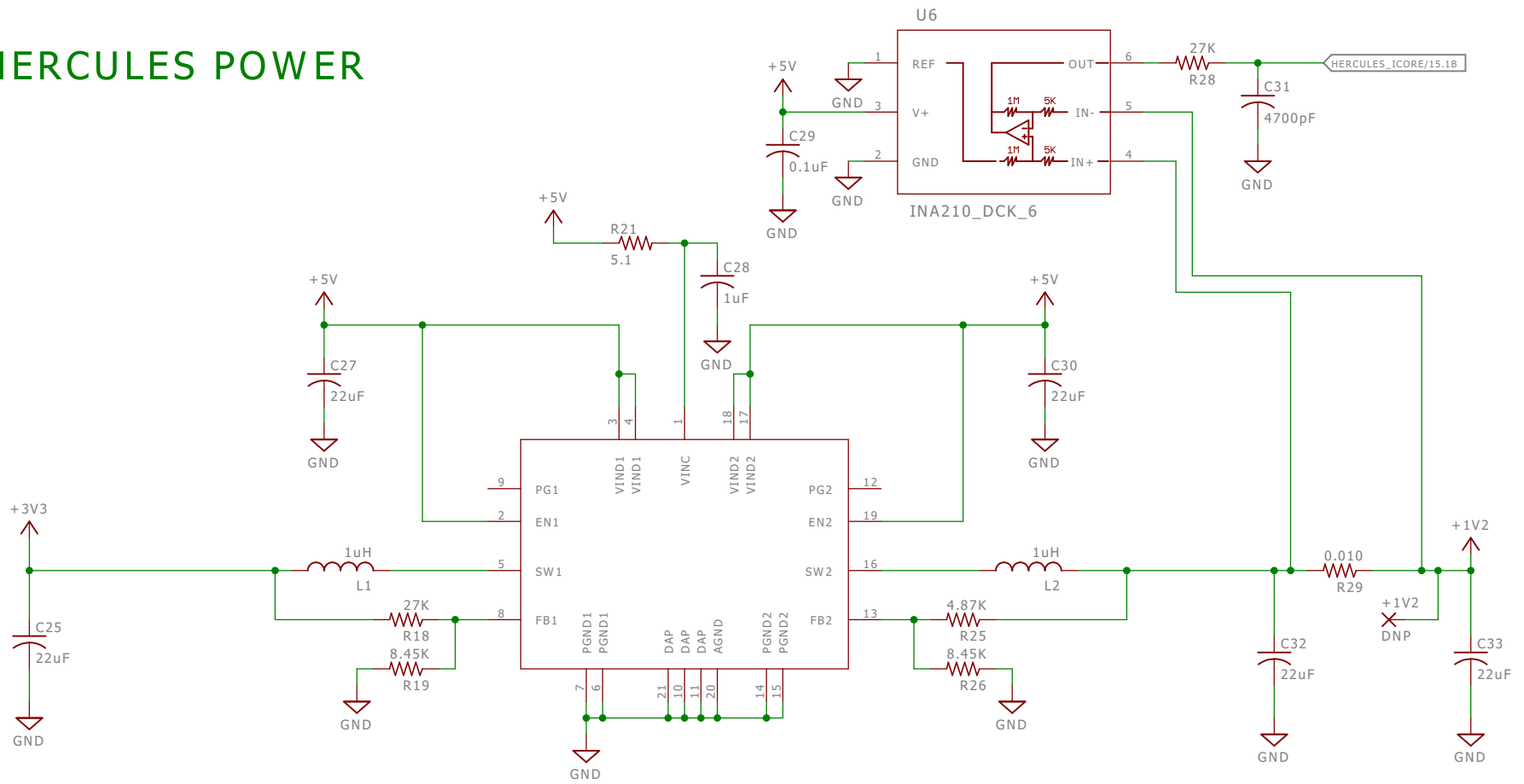


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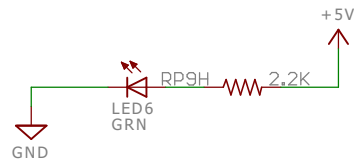


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# HERCULES POWER



# POWER INDICATOR LED

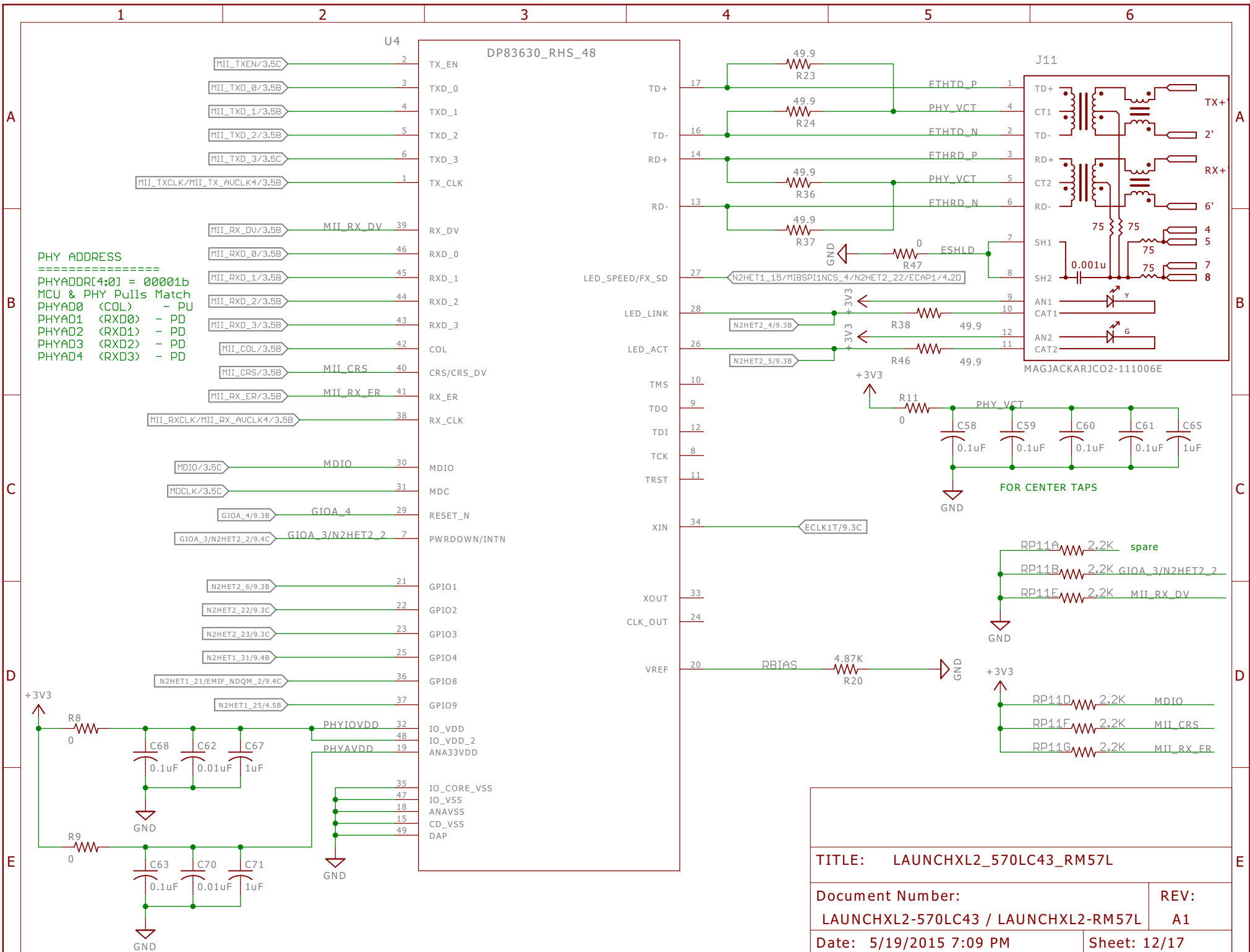


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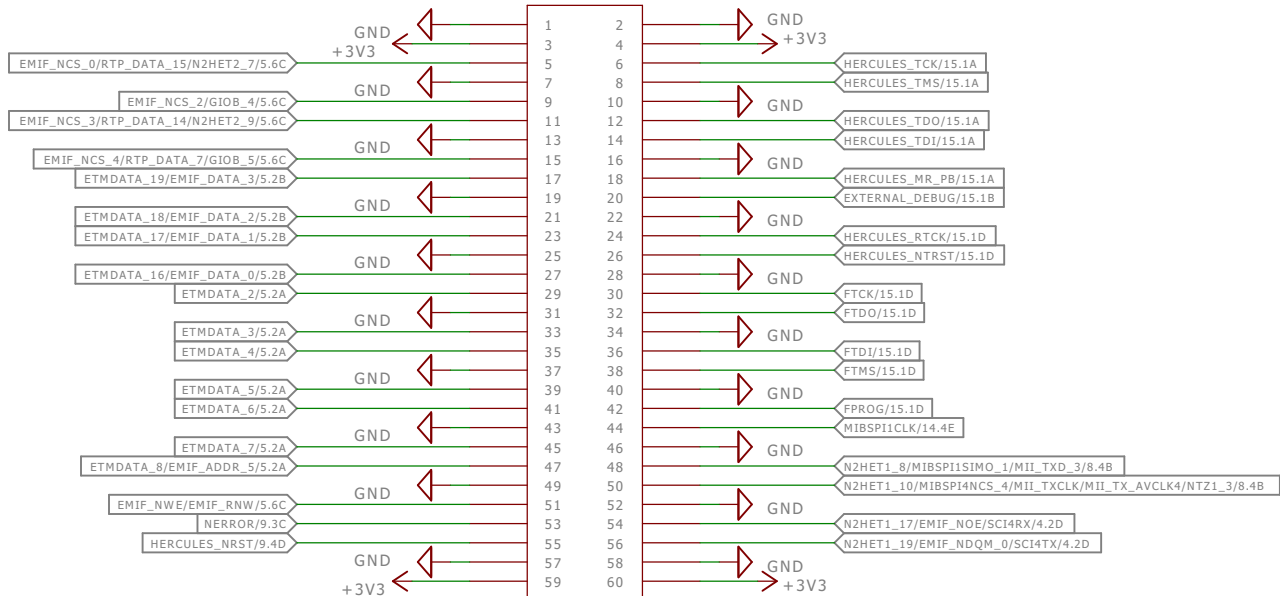
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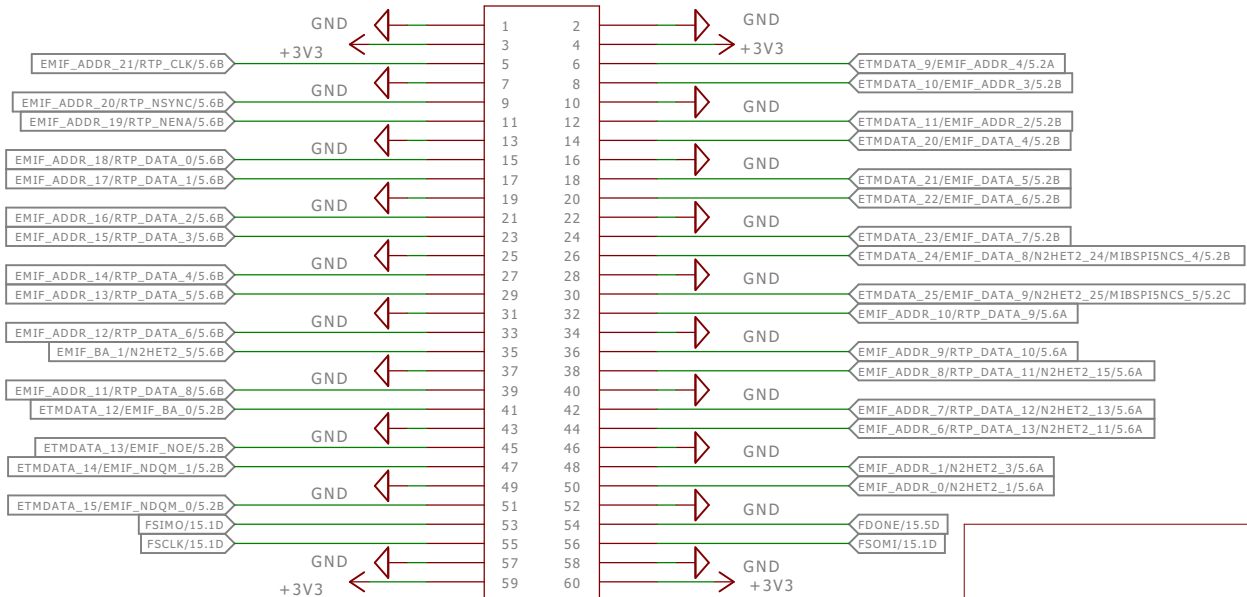
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J12  
DF40C-60DP-0.4V(51)



J13  
DF40C-60DP-0.4V(51)



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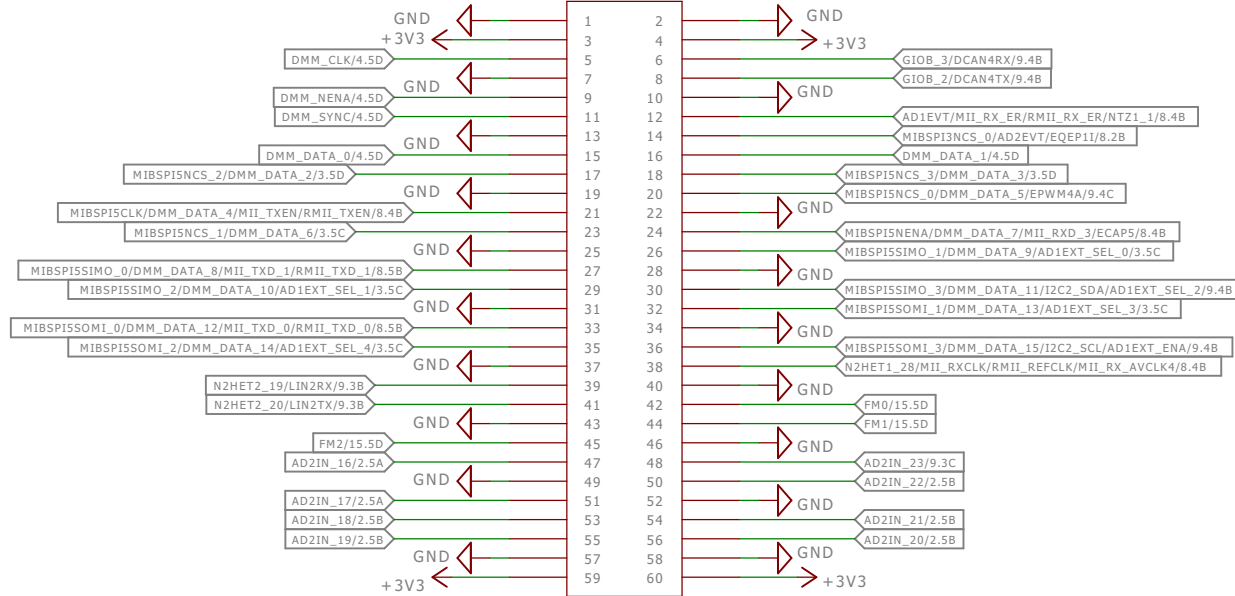
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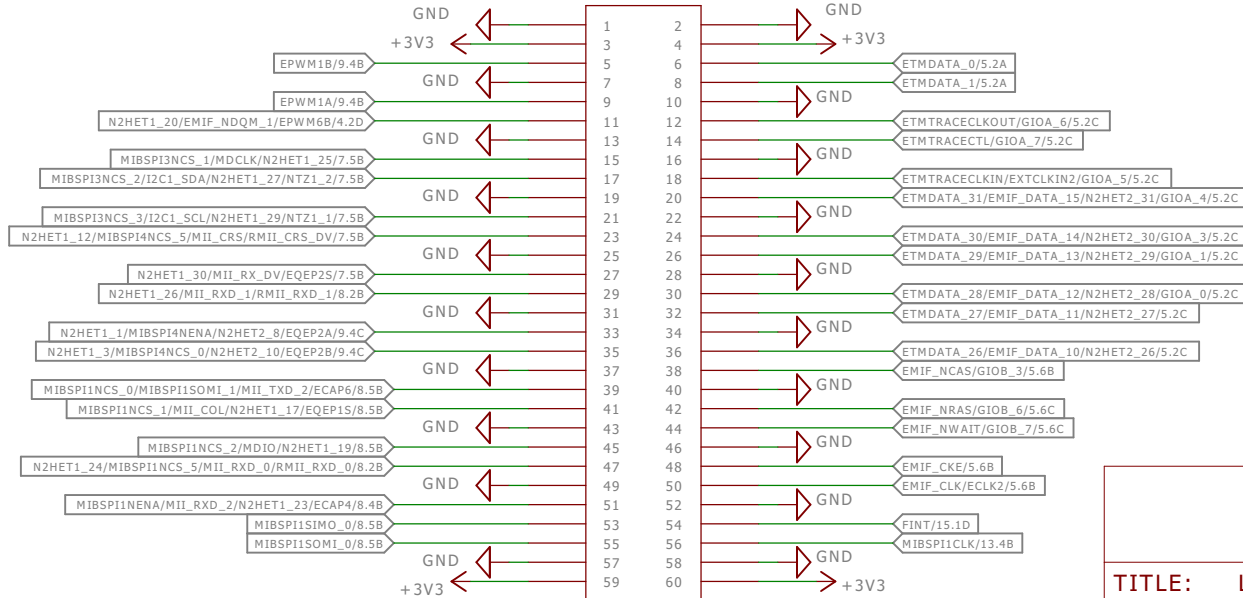
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J14  
DF40C-60DP-0.4V(51)



J15  
DF40C-60DP-0.4V(51)



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LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L

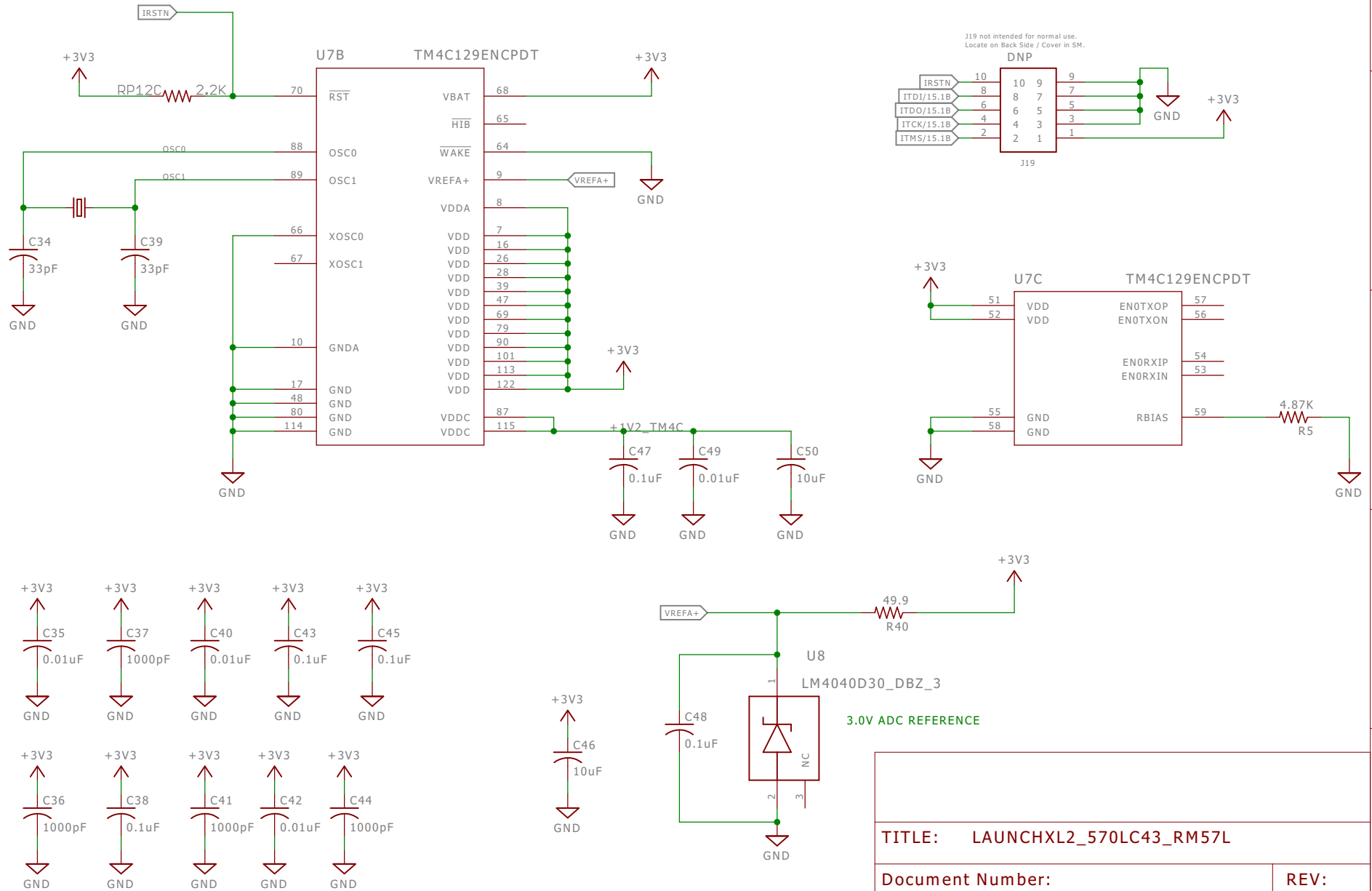
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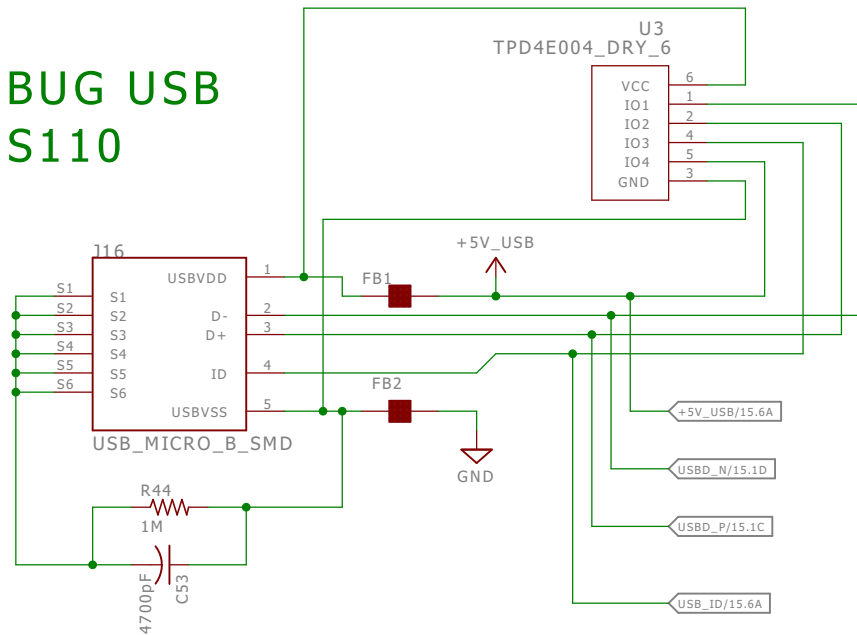
# XDS110 DEBUG PROBE



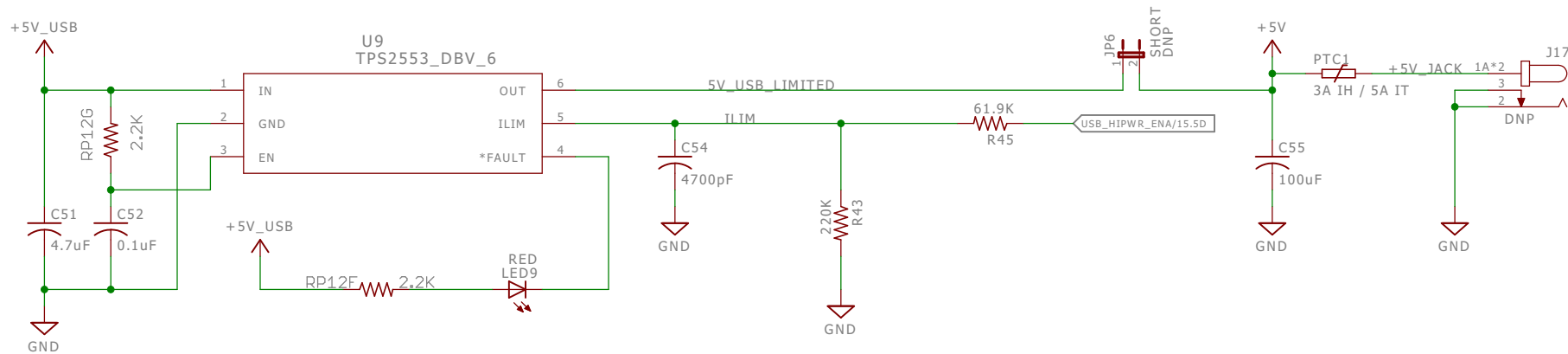
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# DEBUG USB XDS110

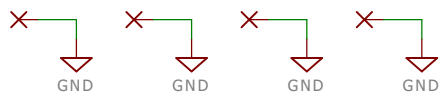


# CURRENT LIMITING FOR BUS POWERED OPERATION



REMOVE JUMPER  
TO POWER THROUGH  
BARREL JACK

## GND POINTS



## FIDUCIALS MNT HOLES



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